

Slit Type Photoresist

EPL 358 Technical Data

2011/01/28



Characteristic



- **Excellent Uniformity**
- **Low Film Loss**
- **Excellent Adhesion**
- **Excellent Strippability**

Evaluation Result



Conditions

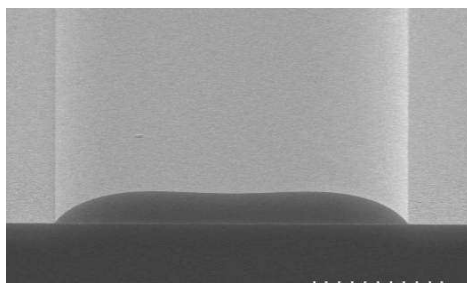
Substrate : 6" Si wafer
Thickness : 1.5um
Prebake : 100°C -90sec
Exposure : Nikon I-line stepper
Development : TMAH 2.38% 60se.

Item	EPL 358
Coating method	Slit
Viscosity (cp)	5
Eth (msec)	47.5
5 μ mEop(mJ/cm ²)	50
Dark Erosion (Å)	490
Resolution (μ m)	2
Adhesion	Ok

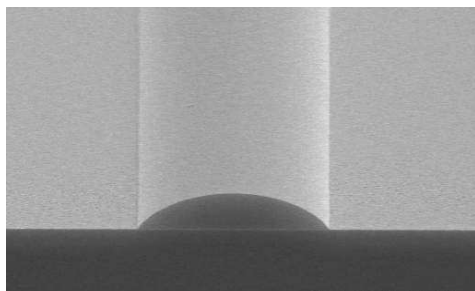
Profile



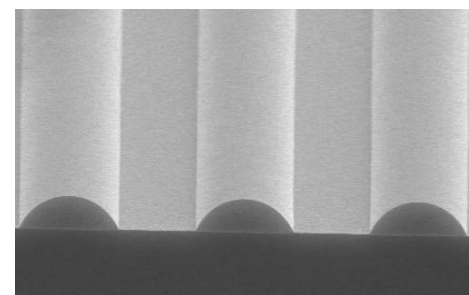
Condition
Substrate : ITO on glass (30Ω)
Thickness : $1.62\mu\text{m}$
Pre bake : 100°C X 90sec.
Exposure : Broad Band
Development : 0.8% KOH X 60sec.



20um



10um



5um

Dry Etching (Mow)



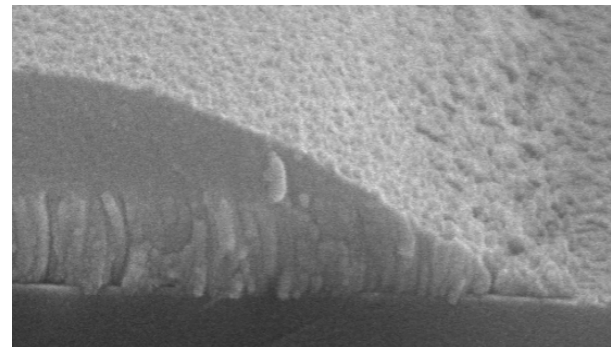
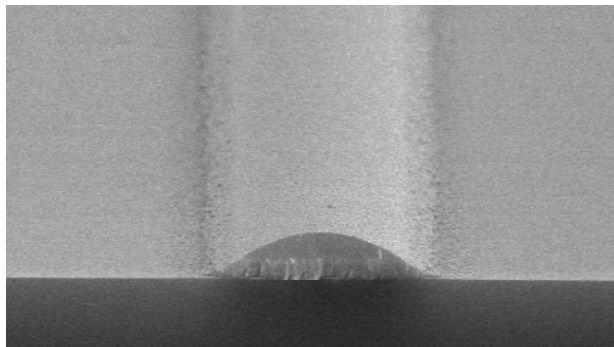
Conditions

Substrate : Mow on Glass(3KÅ,470×370×0.7 mm)

PR Thickness : 1.5μm

Etchant : SF₆ /O₂ /He 220sec.

5um



Adhesion (Al/Cr)



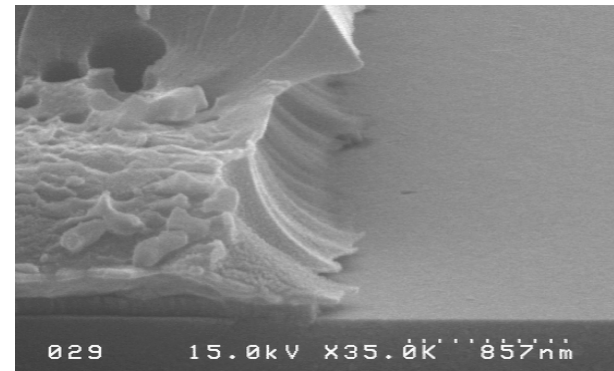
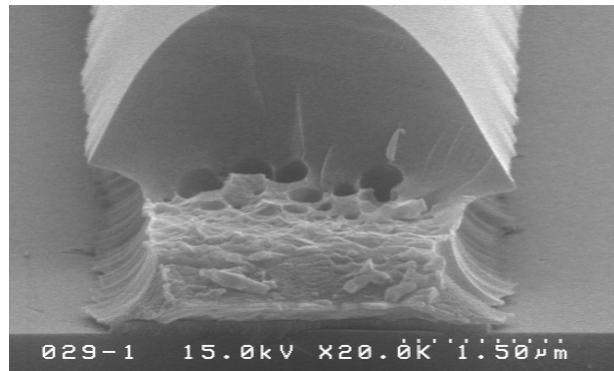
Conditions

Substrate : Al/Cr on Glass(6/1 KÅ,470×370×0.7 mm)

PR Thickness : 1.5μm

Etchant : H_3PO_4 / HNO_3 / CH_3COOH / H_2O 60sec.

5μm



Adhesion (ITO)



Conditions

Substrate : ITO on Glass

PR Thickness : 1.5 μ m

Etchant : HNO₃ /HCl /H₂O

10 μ m

